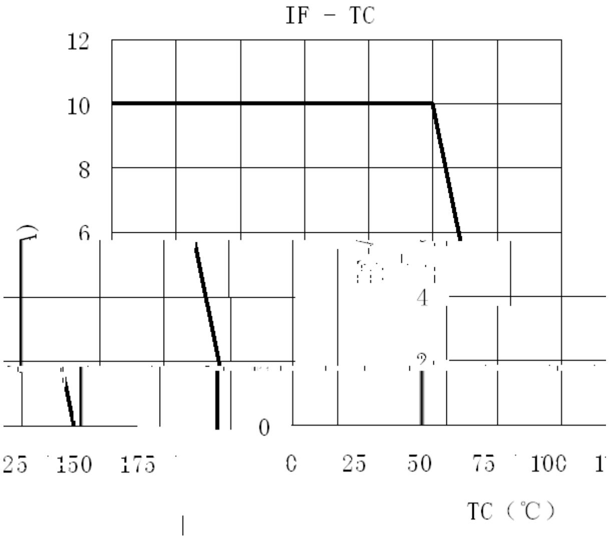
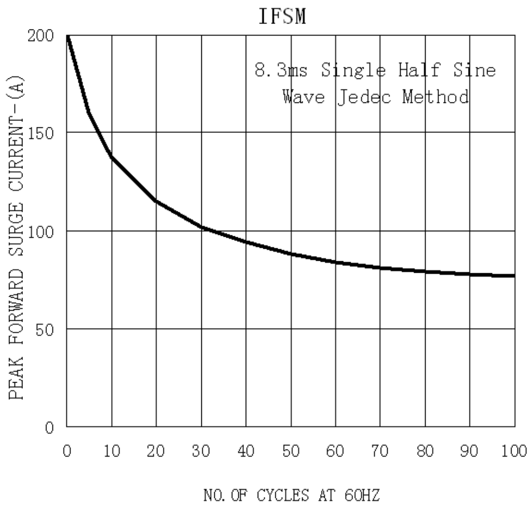
0 **/W**

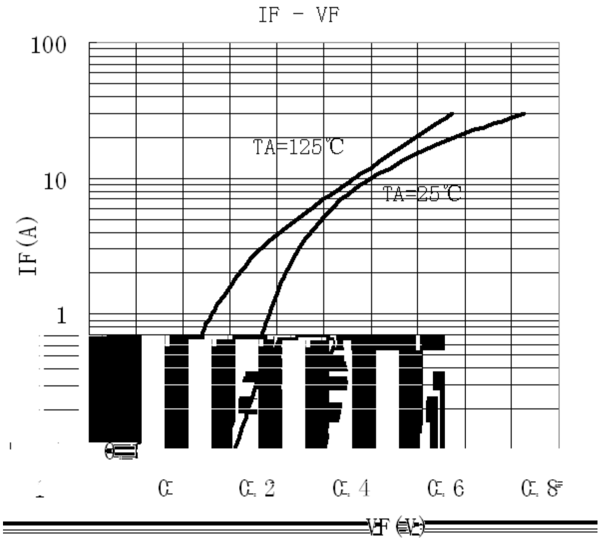
	1.4/W		
Junction and Storage Temperature Range	T_j T_{stg}	-55 +150	

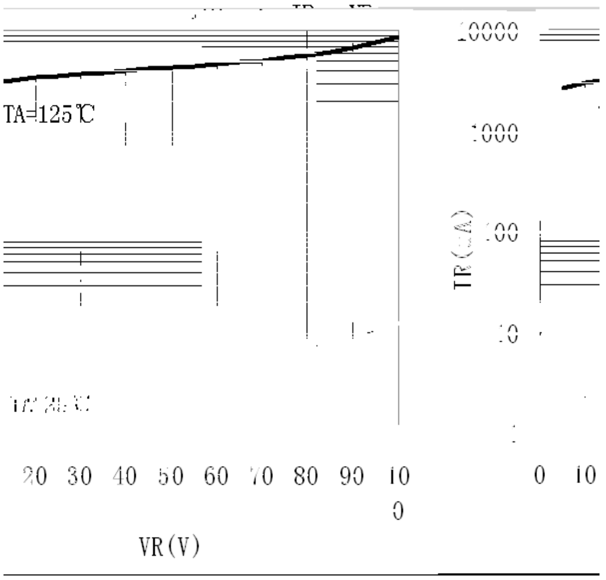
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Reverse Voltage	$V_{(BR)R}$ I	$_R$=1mA(Ta=25) 100			V	
Forward Voltage	V_F	I_F =2A(Ta=25)		0.41	0.45	V
		I_F =10A(Ta=25)	0.58	0.65	V	
		I_F =2A(Ta=125)	0.31	0.40	V	
		I_F =10A(Ta=125)	0.55	0.65	V	
Instantaneous Reverse Current	I_R Note 2	V_R=100V(Ta=125)				

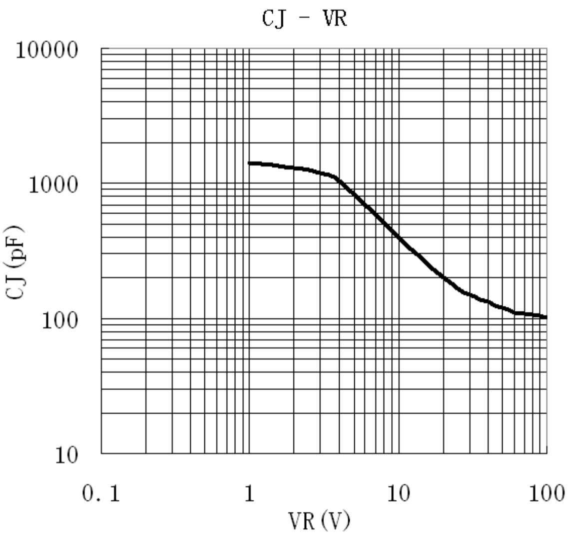
/ Electrical Characteristic Curve







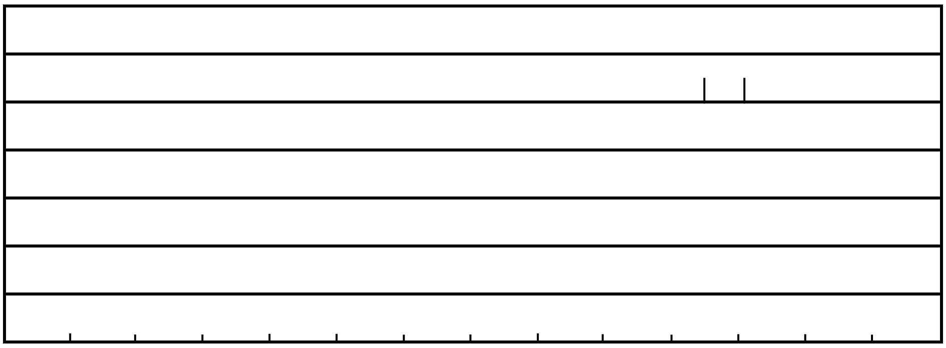




/ Package Dimensions

[redacted]

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



	Note:
1 150 180 60 90sec;	1.Preheating:150~180 , Time:60~90sec.
2 245 5 5 0.5sec;	2.Peak Temp.:245 5 , Duration:5 0.5sec.
3 2 10 /sec.	3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260 5 10 1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension (unit mm^3)		
	Units/Reel /	Reels/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Reel	Inner Box	Outer Box
TO-277	5,000	3	15,000	6	90,000	13 ×12	360×360×50	380×335×366

/ Notices